

IN THE CLAIMS:

Claims 1-51 and 55-62 were previously cancelled. None of the claims have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

Listing of Claims:

1.-51. (Canceled)

52. (Previously presented) A socket contact formation process for forming a plurality of socket contacts in a substrate, the plurality of socket contacts having a spacing therebetween for mating with the contacts of an IC chip for use in the testing thereof, comprising:
forming a contact head from a conductive material as at least one member of a socket contact having at least two members forming portions thereof, the contact head for contacting one of the contacts of the IC chip for use in the testing thereof;
forming a contact body from a doped semiconductive material configured to be electrically conductive as a member of a socket contact having at least two members forming portions thereof, the contact body formed from a doped semiconductive material for use in the testing of the IC chip; and
joining the contact head and the contact body forming a socket contact having at least two members forming portions thereof, the joined contact head and the contact body having at least a portion of the contact head contacting at least a portion of a contact of the IC chip during the testing thereof.

53. (Previously presented) The process in claim 52, wherein:
forming a contact head comprises stamping a metal element as at least one member of a socket
contact having at least two members forming portions thereof;
forming a contact body comprises etching silicon having at least a portion thereof doped to be
electrically conductive as at least one member of a socket contact having at least two
members forming portions thereof; and
joining the contact head and the contact body further comprises adhering the contact head onto
the contact body forming a socket contact having at least two members forming portions
thereof.

54. (Previously presented) The process in claim 52, wherein joining the contact head
and the contact body further comprises depositing a metal over a doped silicon surface for a
socket contact having at least two members forming portions thereof.

55.-62. (Canceled)